

09/982,221

Amend claims 19 and 22 as follows:

- 1 19. (Twice Amended) A multi-layer substrate structure comprising:
- 2 at least one layer having generic electrical features altered to customize said
- 3 layer,
- 4 wherein said electrical features include vias,
- 5 wherein said vias are selectively filled with a conducting material and an
- 6 insulating material.

- 1 22. (Twice Amended) The multi-layer substrate structure in claim 19, further
- 2 comprising a second layer similar to said layer and having said generic electrical
- 3 features including vias altered differently than said layer to customize said
- 4 second layer differently than said layer, wherein said vias in said second layer
- 5 are selectively filled with a conducting material and an insulating material.

Add new claims 29 and 30 as follows:

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